

**10/561883**

**IAP20 Rec'd PCT/PTO 23 DEC 2005**

**IN THE UNITED STATES OF PATENT AND TRADEMARK OFFICE**

In re application of	)	Adrian BOYLE et al
For	)	Die Bonding
International Application Serial No.	)	PCT/EP2004/007161
International Filing Date:	)	July 1, 2004

**FIRST PRELIMINARY AMENDMENT**

Mail Stop: PCT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Please amend the above identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims that begins on page 2 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.